Product Data Sheet

ATCA Signal AMC B+, Part No. 512-22170-453

Illustration similar

Parallel Press-fit Direct Connector High Speed

- without Peg
- 170 contacts
- Press-fit
- pitch 0.75 mm
- data transfer rate 12.5 Gbit/s
- according to PICMG specifications

» to product on www.ept.de

» to product group Advanced TCA

Technical Specifications

Basics

Specification	PICMG®AMC.0 R2.0
No. of Contacts	170
Termination Technology	Press-fit
Termination Length	2.0 mm
Operating Temperature Range	-55°C to +105°C

Material

Insulator Material	LCP, UL 94 V-0
Contact Material	Copper alloy
Plating	PdNi + Au flash over Ni

Mechanical

Pitch	0.75 mm
Mating Force	max. 100 N
Separating Force	max. 65 N
Durability	200 mating cycles

Electrical

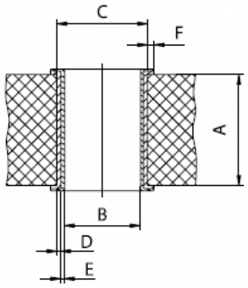
Operational Current	1.52 A @ 70°C max. 30°C temperature rise
Clearance and Creepage	min. 0.1 mm
Insulation Resistance	10^8 Ω
Test Voltage	80 V r.m.s
Data Transfer Rate	12.5 Gbit/s
Impedance	100 Ω± 10%

Approval / Compliance

UL file	E130314
Environment	RoHS compliant

Hole Specifications

Plated through-hole according to IEC 60352-5



Material	**chem. Sn printed circuit boards**
Nominal Hole	**Ø 0.55 mm**
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 0.55 ±0.05 mm
C Drill Hole	0.64 ±0.01 mm
D Cu Plating	min. 25 µm
E Surface	imm. Sn plating, max. 1.5 µm
F Annular Ring	min. 0.15 mm

Material	**Ni, Au printed circuit boards**
Nominal Hole	**Ø 0.55 mm**
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 0.55 ±0.05 mm
C Drill Hole	0.64 ±0.01 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au plating, 0.05 - 0.2 µm Au over 2.5 - 5 µm Ni
F Annular Ring	min. 0.15 mm

Drawings

Component data in 2D and 3D format you can download here:

» PDF » 3D IGES » 3D STEP » 3D PDF